

Schottky Barrier Diode

# CMS30I30A

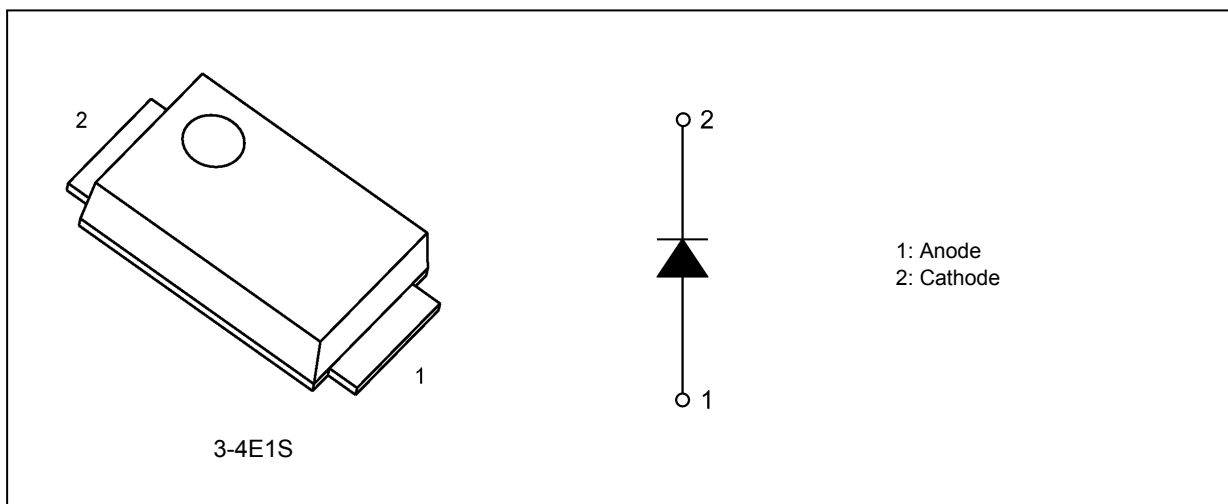
## 1. Applications

- Secondary Rectification in Switching Regulators
- Reverse-Current Protection in Mobile Devices

## 2. Features

- (1) Peak forward voltage:  $V_{FM} = 0.49 \text{ V (max)@}I_{FM} = 3 \text{ A}$
- (2) Average forward current:  $I_{F(AV)} = 3 \text{ A}$
- (3) Repetitive peak reverse voltage:  $V_{RRM} = 30 \text{ V}$
- (4) Small, thin package suitable for high-density board assembly  
Toshiba Nickname: M-FLAT™

## 3. Packaging and Internal Circuit



## 4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25^\circ\text{C}$ )

Characteristics	Symbol	Note	Rating	Unit
Repetitive peak reverse voltage	$V_{RRM}$	—	30	V
Average forward current	$I_{F(AV)}$	(Note 1)	3	A
Non-repetitive peak forward surge current	$I_{FSM}$	(Note 2)	30	
Junction temperature	$T_j$	—	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$		-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1:  $T_t = 102 \text{ }^\circ\text{C}$ , square wave ( $\alpha = 180^\circ$ ),  $V_R = 15 \text{ V}$

Note 2:  $f = 50 \text{ Hz}$ , half-sine wave

Start of commercial production  
2010-10

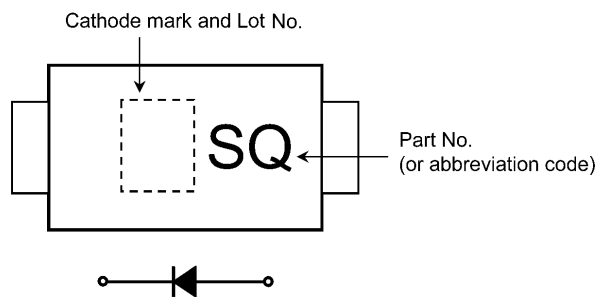
**5. Thermal Characteristics**

Characteristics	Symbol	Note	Test Condition	Max	Unit
Thermal resistance (junction-to-ambient)	$R_{th(j-a)}$	—	Device mounted on a ceramic board (board size: 50 mm × 50 mm) (soldering land size: 2 mm × 2 mm) (board thickness: 0.64 mm)	60	°C/W
		—	Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land size: 6 mm × 6 mm) (board thickness: 1.6 mm)	135	
Thermal resistance (junction-to-lead)	$R_{th(j-l)}$	—	Junction to cathode lead	16	

**6. Electrical Characteristics (Unless otherwise specified,  $T_a = 25^\circ\text{C}$ )**

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Peak forward voltage	$V_{FM(1)}$	—	$I_{FM} = 0.5 \text{ A}$ (pulse measurement)	—	0.3	—	V
	$V_{FM(2)}$	—	$I_{FM} = 1 \text{ A}$ (pulse measurement)	—	0.33	—	
	$V_{FM(3)}$	—	$I_{FM} = 3 \text{ A}$ (pulse measurement)	—	0.4	0.49	
Repetitive peak reverse current	$I_{RRM(1)}$	—	$V_{RRM} = 5 \text{ V}$ (pulse measurement)	—	14	—	$\mu\text{A}$
	$I_{RRM(2)}$	—	$V_{RRM} = 30 \text{ V}$ (pulse measurement)	—	28	100	
Junction capacitance	$C_j$	—	$V_R = 10 \text{ V}$ , $f = 1 \text{ MHz}$	—	82	—	pF

**7. Marking**



**Fig. 7.1 Marking**

Marking Code	Part Number
SQ	CMS30I30A

## 8. Usage Considerations

- (1) Schottky barrier diodes (SBDs) have reverse current greater than other types of diodes. This makes SBDs more vulnerable to damage due to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.
- (2) The absolute maximum ratings are rated values that must not be exceeded during operation, even for an instant. The following are the recommended general derating methods for designing a circuit board using this device.

$V_{RRM}$ : Use this rating with reference to (1) above.  $V_{RRM}$  has a temperature coefficient of 0.1%/°C at low temperatures. Take this coefficient into account when designing a circuit board that will be operated in a low-temperature environment.

$I_{F(AV)}$ : We recommend that the worst-case current be no greater than 80% of the absolute maximum rating of  $I_{F(AV)}$  and that the worst-case junction temperature,  $T_j$ , be kept below 120°C. When using this device, allow margins, referring to the  $T_{a(max)}-I_{F(AV)}$  curve.

$I_{FSM}$ : This rating specifies peak non-repetitive forward surge current. This only applies to an abnormal operation, which seldom occurs during the lifespan of a device.

$T_j$ : Derate device parameters in proportion to this rating in order to ensure high reliability. We recommend that the junction temperature ( $T_j$ ) of a device be kept below 120°C.

- (3) Thermal resistance (junction-to-ambient) varies with the mounting conditions of a device on a circuit board. An appropriate thermal resistance value should be used, considering the heatsink, circuit board design and land pattern dimensions (provided for reference only).
- (4) For other design considerations, see the Rectifiers databook or the Toshiba Semiconductor website.

## 9. Land Pattern Dimensions (for reference only)

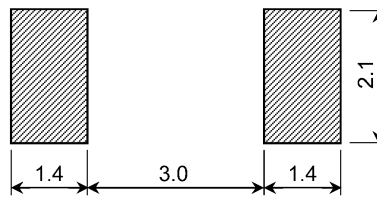
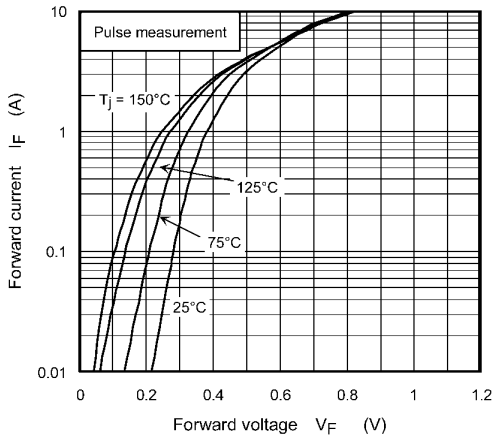
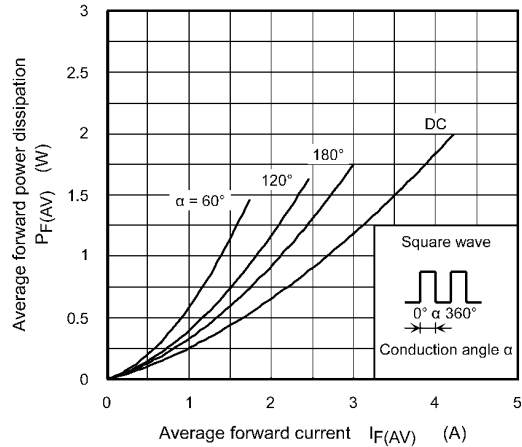


Fig. 9.1 Land Pattern Dimensions (for reference only) (Unit: mm)

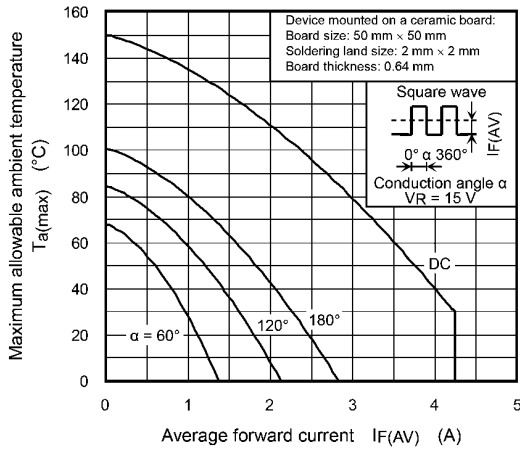
**10. Characteristics Curves (Note)**



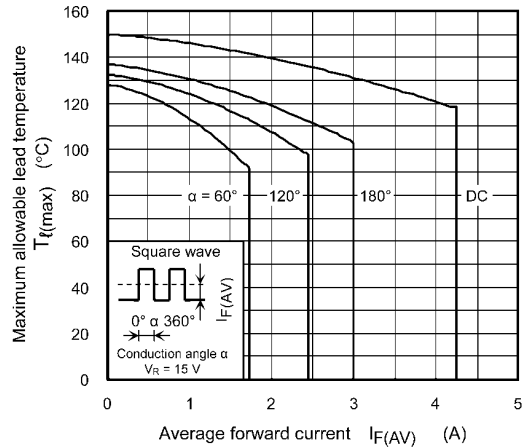
**Fig. 10.1  $I_F - V_F$**



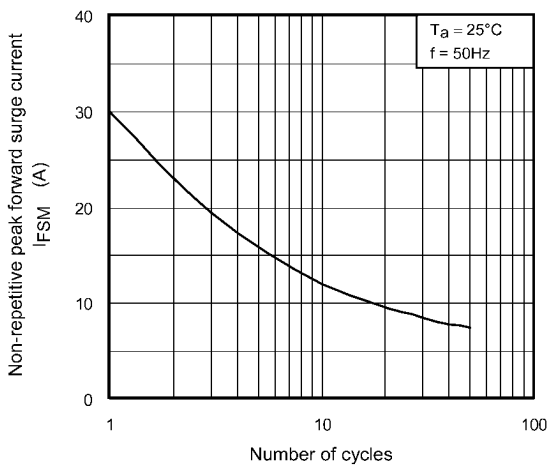
**Fig. 10.2  $P_{F(AV)} - I_{F(AV)}$**



**Fig. 10.3  $T_{a(max)} - I_{F(AV)}$**



**Fig. 10.4  $T_{l(max)} - I_{F(AV)}$**



**Fig. 10.5 Surge current**

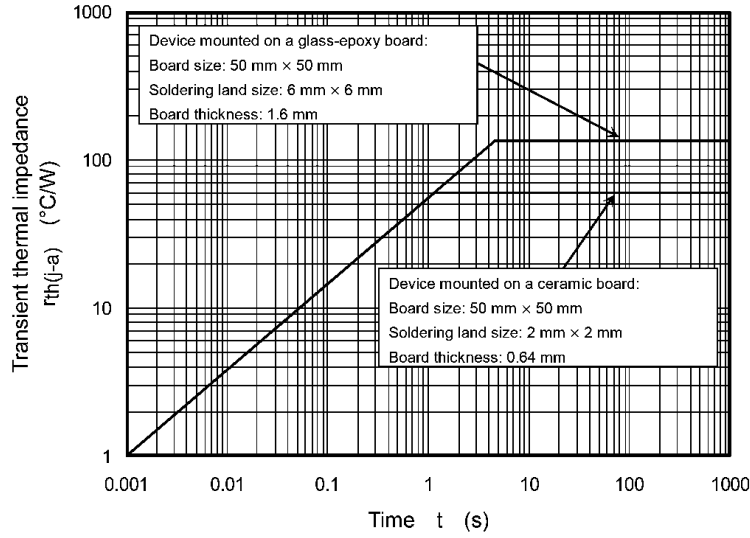


Fig. 10.6  $r_{th(j-a)} - t$

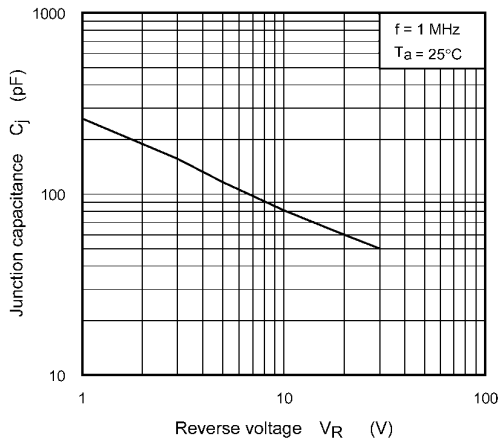


Fig. 10.7  $C_j - V_R$

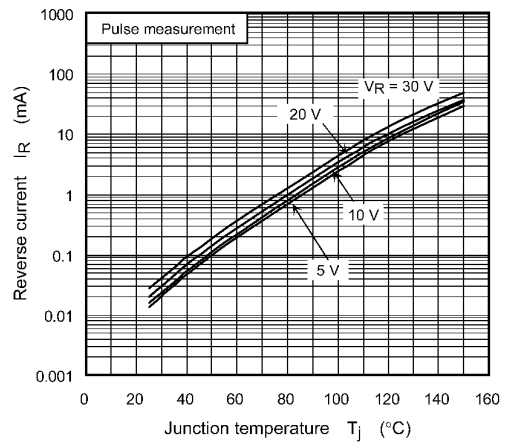
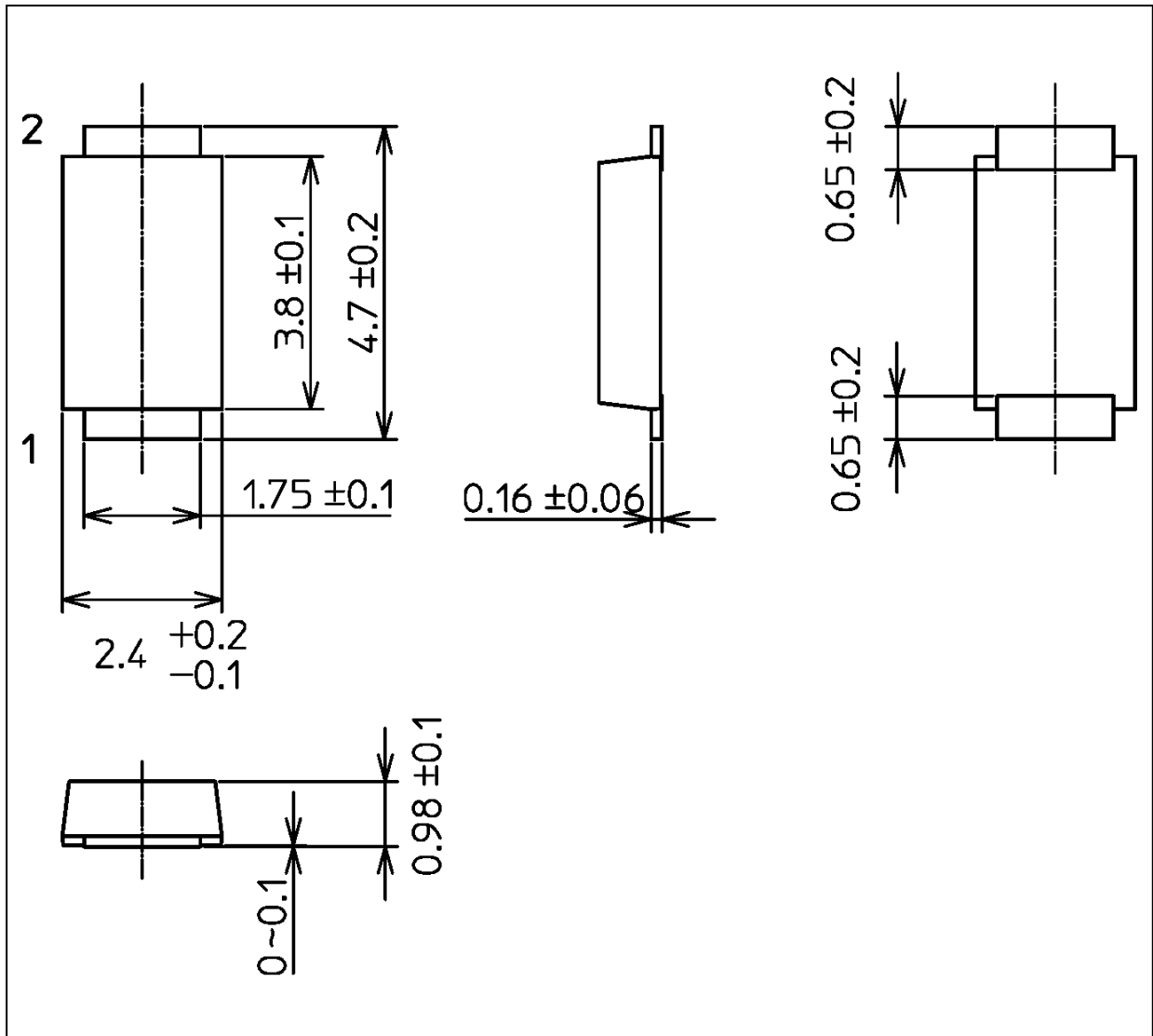


Fig. 10.8  $I_R - T_j$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.023 g (typ.)

Package Name(s)
TOSHIBA: 3-4E1S
Nickname: M-FLAT

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